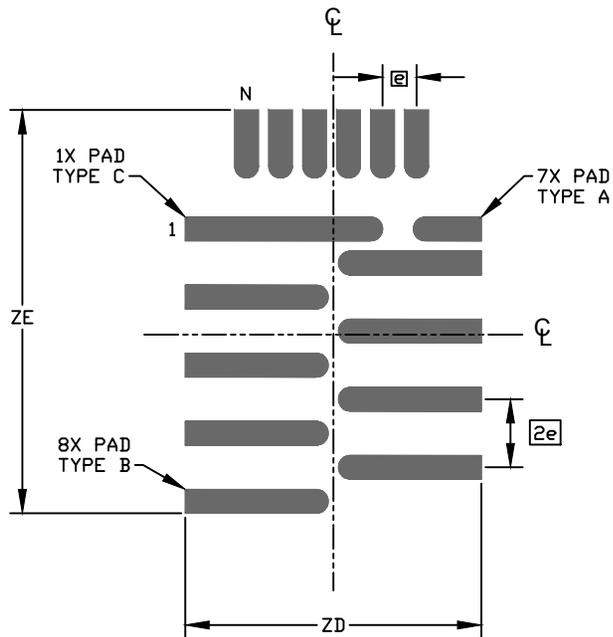
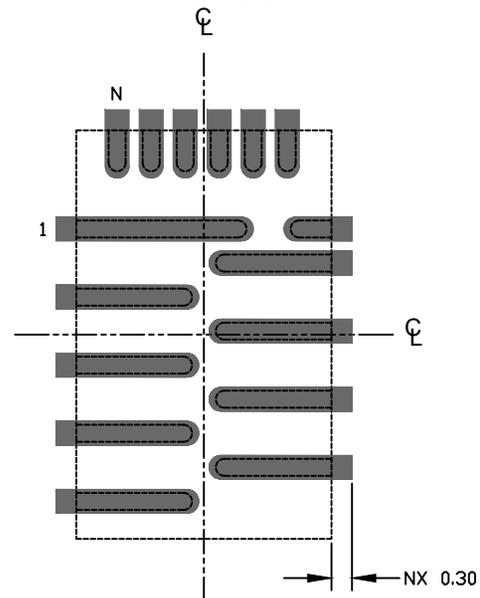


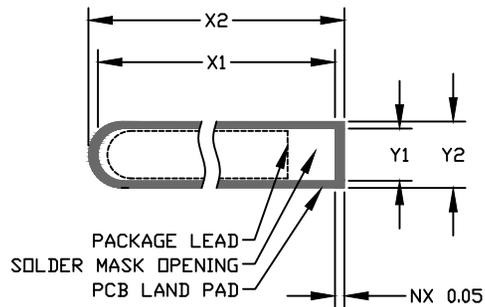
RECOMMENDED LAND PATTERN



PACKAGE OVERLAY



PAD DETAIL INFORMATION



DIM	MILLIMETERS			INCHES		
	MIN	NDM	MAX	MIN	NDM	MAX
e	0.50 BSC			.020 BSC		
N	16 PINS			16 PINS		
ZD	4.35 REF			.171 REF		
ZE	5.92 REF			.233 REF		

DIM	MILLIMETERS			INCHES		
	TYPE A	TYPE B	TYPE C	TYPE A	TYPE B	TYPE C
Y1	0.28	0.28	0.28	.011	.011	.011
Y2	0.35	0.35	0.35	.014	.014	.014
X1	0.90	2.00	2.80	.035	.079	.110
X2	1.00	2.10	2.90	.039	.083	.114

NOTES:

1. REFERENCE PKG. OUTLINE: 21-0986
2. LAND PATTERN COMPLIES TO: IPC7351A.
3. ALL DIMENSIONS APPLY TO PbFREE (+) PKG. CODE ONLY.
4. ALL DIMENSIONS IN MM.
5. FIND ADDITIONAL SOLDER STENCIL RECOMMENDATION IN APPENDIX.

-DRAWING NOT TO SCALE-



TITLE:  
PACKAGE LAND PATTERN,  
[P163A6F+1 / P163A6F+2] FCQFN

APPROVAL

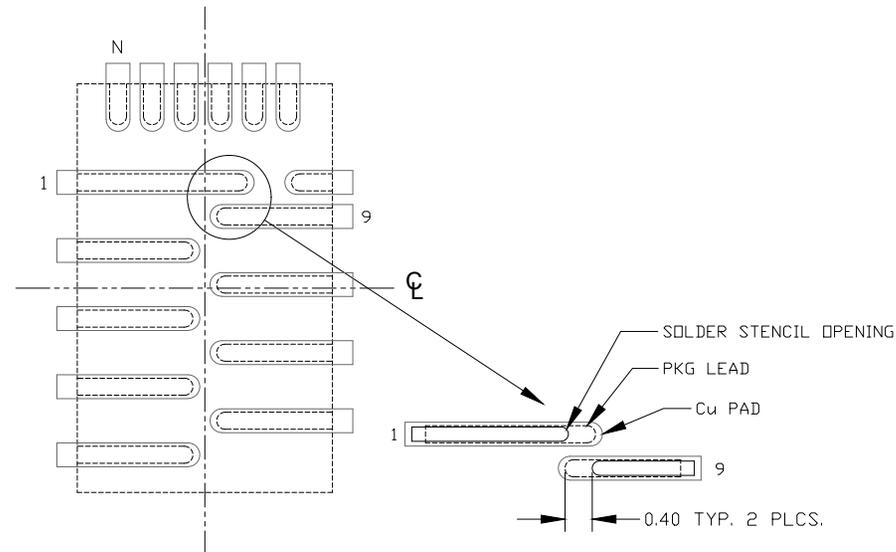
DOCUMENT CONTROL NO.  
90-0490

REV. 1/2  
C

This document (including dimensions, notes & specs) is a recommendation based on typical circuit board manufacturing parameters. Since land pattern design depend on many factors unknown to Maxim (eg. user's board manufacturing specs), user must determine suitability for use. This document is subject to change without notice. Contact technical support at <http://www.maximintegrated.com/support> for further questions.

# APPENDIX

## SOLDER STENCIL RECOMMENDATION (LEADS 1 AND 9)



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PACKAGE LAND PATTERN,  
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